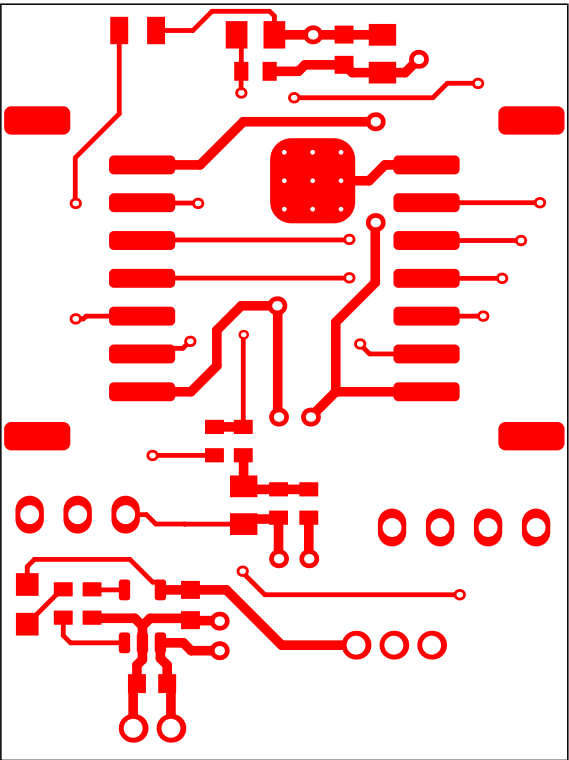
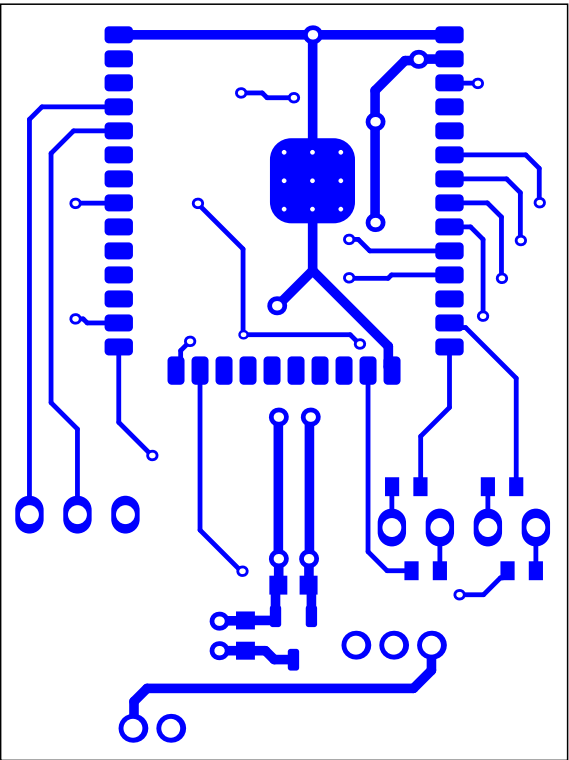


# Motherboard Bracelet

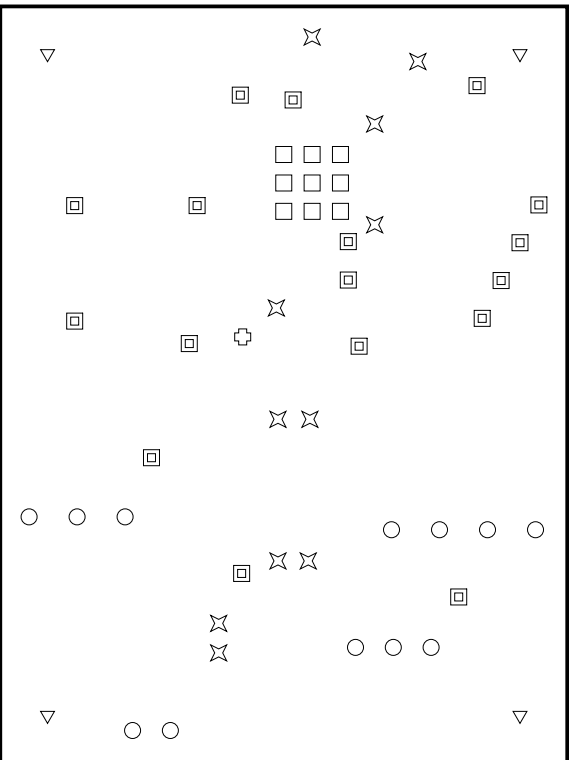
Top Layer (Scale 2.5:1)



Bottom Layer (Scale 2.5:1)



Drill Drawing View (Scale 2.5:1)



Drill Table

Symbol	Count	Hole Size	Plated	Hole Tolerance
□	9	0.25mm	Plated	
⊕	1	0.25mm	Plated	
▣	17	0.30mm	Plated	
✕	11	0.50mm	Plated	
○	12	1.00mm	Plated	
▽	4	2.50mm	Non-Plated	
54 Total				

Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.01mm	Solder Resist	Solder Mask	GTS
Copper	Top Layer	0.04mm		Signal	GTL
Core		1.50mm	Core-043	Dielectric	
Copper	Bottom Layer	0.04mm		Signal	GBL
Surface Material	Bottom Solder	0.01mm	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
Total thickness: 1.59mm					

	WF TECNOLOGIA			Revisão	Data	Responsável	Histórico
	Natan Figueiredo			R00	17/02/202	Natan MF	=HIST01
	+55 41 99558-4388						=HIST02
	eng.figueiredo@gmail.com						=HIST03
	Projeto Motherboard Bracelet						=HIST04
Elaboração	Roger	Aprovação	Marlio	Layout	Natan Figueiredo		
Código		Revisão	R00	Folha	1/1		
Data	5/28/2024	Horário	8:41 PM	Tamanho	A3		
Arquivo	E:\WF_Tecnologia\Roger_Lakoski_Mestrado\RL_Motherboard_Bracelet\Motherboard_Bracelet_Fabrication.PCBDwf						